SPECIFICATION

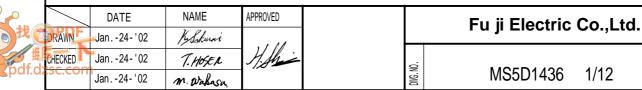
Device Name : SILICON DIODE

Type Name : YG962S6R

: MS5D1436 Spec.No.

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Fuji Electric Co.,Ltd. Matsumoto Factory



Revised Records

Date	Classi - fication	Ind.	Content	Applied date	Drawn	Checked	Checked	Approved
APR26	enactment			Issued		K.		T.
-2001				date		SAKURAI		HOSEN
JAN24	alteration	а	·add test items	Issued	V 01 .	Tuca	. 0	, , , , , ,
-2002				date	Moskman	T. HOSER	M. Wakasa	Ash
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Fuji Electric Co.,Ltd.

DING.NO.

MS5D1436

This specification provides the ratings and the test requirement for FUJI SILICON DIODE YG962S6R

2. Application

PFC circuit(current continuous mode)

This diode is a product which optimizes the diode characteristic for the PFC circuit. This product is a product by which the trr characteristic was valued more than VF though there is a relation of the trade-off up to VF and Trr. The total loss of the PFC circuit can be suppressed by shortening trr.

3. OUT VIEW, MARKING, MOLDING RESIN, CHARACTERISTICS

(1) Out view is shown MS5D1436 9/12

(2) Marking is shown MS5D1436 9/12

It is marked to type name or abbreviated type name, polarity and Lot No.

(3) Molding resin

Epoxy resin UL:V-0

(4) Characteristics is shown MS5D1436 10/12~12/12

4. RATINGS

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4.1 MAXIMUM RATINGS

ITEM	SYMBOL	CONDITIONS	RATINGS	UNITS
Repetitive peak reverse voltage	VRRM		600	V
Non-repetitive peak reverse voltage	V_{RSM}		600	V
Isolating voltage	Viso	Terminals-to-Case,AC.1min	1500	V
Surge peak forward current	lps	tw 200ns	15	Α
Peak forward current	lp		10	Α
Average output current	lo	Square wave duty =1/2 Tc = 102	3.5	А
Non-repetitive surge current	IFSM	Sine wave, 10ms	25	Α
Operating junction temperature	Tj		150	°C
Storage temperature	Tstg		-40~ + 150	°C

4.2 ELECTRICAL CHARACTERISTICS (at Ta=25 unless otherwise specified.)

ITEM	SYMBOL	CONDITIONS	MAXIMUM		UNITS
Reverse recovery peak current	I _{RP}	IF=5A,-di/dt=200A/ μ s,VR=380V Tj=100	Тур.	2.0	Α
Reverse recovery time	trr	IF=0.1A,I _R =0.2,Irec=0.05A	Max.	25.0	ns
Forward voltage	VF	IF= 10 A	Max.	5.0	V
Reverse current	lR	VR = VRRM	Max.	50.0	μА
Thermal resistance	Rth(j-c)	Junction to case	Max.	5.0	°C/W

4.3 MECHANICAL CHARACTERISTICS

Mounting torque	Recommended torque	0.3 ~ 0.5	N∙m
Approximate mass		2.0	g

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5.TEST

	Test	Test	Testing methods and Conditions	Reference		Acceptance
	No.	Items		Standard	number	number
\vdash			10.114	EIAJ ED4701		
	1	Terminal	Pull force			
		Strength	TO-220,TO-220F: 10N		_	
		(Tensile)	TO-3P,TO-3PF,TO-247 : 25N	A-111A	5	
			TO-3PL : 45N	method 1		
			T-Pack,K-Pack: 10N			
			Force maintaining duration :30±1s			
	2	Terminal	Load force			
		Strength	TO-220,TO-220F : 5N			
		(Bending)	TO-3P,TO-3PF,TO-247 : 10N	A-111A	5	
			TO-3PL: 15N	method 3		
			T-Pack,K-Pack : 5N			
║╻╽			Number of times :2times(90deg./time)			(5.1)
Mechanical test	3	Mounting	Screwing torque value: (M3)		_	(0:1)
 		Strength	TO-220,TO-220F : 40±10N	A-112	5	
iš			TO-3P,TO-3PF,TO-247 : 50±10N	method 2		
ll ar			TO-3PL: 70±10N			
	4	Vibration	frequency: 100Hz to 2kHz			
∥∑			Acceleration: 100m/s ²	A-121	5	
			Sweeping time: 4min./1 cycle			
			4times for each X,Y&Z directions.			
	5	Shock	Peak amplitude: 15km/s ²	A-122		
			Duration time : 0.5ms	test code D	5	
			3times for each X,Y&Z directions.			
	6	Solderability	Solder temp. : 235±5°C			
			Immersion time : 5±0.5s	A-131A		
			Each terminal shall be immersed in	test code A	5	
			the solder bath within 1 to 3.0mm from			
			the body.			
	7	Resistance to	Solder temp. : 260±5°C			
		Soldering Heat	Immersion time : 10±1s	A-132	5	
			Number of times : 1times			

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ormation herein	shall be neither	way whatsoever	the manufacturin	of Fuji Electric
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	Test	Test	Testing methods and Conditions	Reference	Sampling	Acceptance
	No.	Items		Standard	number	number
				EIAJ ED4701		
	1	High Temp.	Temperature :⊺stg max	B-111A	22	
		Storage	Test duration: 1000h			
	2	Low Temp.	Temperature : Tstg min	B-112A	22	
		Storage	Test duration: 1000h			
	3	Temperature	Temperature: 85±2°C	B-121A		
		Humidity	Relative humidity: 85±5%	test code C	22	
		Storage	Test duration: 1000h			
	4	Temperature	Temperature: 85±2°C			
		Humidity	Relative humidity: 85±5%	B-122A	22	
		Bias	Bias Voltage: V _{RRM} × 0.8	test code C		
Endurance test			Test duration: 1000h			
l e	5	Unsaturated	Temperature : 120±2°C			(0:1)
anc I		Pressurized	Relative humidity: 85±5%	B-123A	22	` ,
l in		Vapor	Vapor pressure : 170kPa	test code B		
l in		·	Test duration : 96h			
Ш	6	Temperature	High temp.side : Tstg max			
		Cycle	Room temp. : 5 ~ 35			
			Low temp.side : Tstg min	B-131A	22	
			Duration time: HT 30min,RT 5min LT 30min			
			Number of cycles: 100 cycles			
	7	Thermal Shock	Fluid : pure water(running water)			
			High temp.side: 100+0/-5°C	B-141A	22	
			Low temp.side : 0+5/-0°C	test code A		
			Duration time : HT 5min,LT 5min			
			Number of cycles : 100 cycles			
	8	Steady state	Ta=25±5°C			
		Operating life	Rated load	D-402	22	
		_	Test duration: 1000h			
	9	Intermittent	Tj=Tjmax ~50			
		Operating	3min ON, 3min OFF	D-403	22	(0:1)
		Life	Test duration: 10000cy			, ,
	10	High Temp.	Temperature : Ta= 100 °C			
		Reverse Bias	Bias Voltage : V _R =V _{RRM} duty=1/2	D-404	22	
			Test duration: 1000h			

Failure Criteria	I_R	USL x 5
	V_F	USL x 1.1

USL:Upper specification Limit

6.Cautions

- · Although Fuji Electric is continually improving product quality and reliability, a small percentage of semiconductor products may become faulty. When using Fuji Electric semiconductor products in your are requested to take adequate safety measures to prevent the equipment from causing physical injury, fire, or other problem in case any of the products fail.It is recommended to make your design fail-safe,flame retardant.and free of malfunction.
- The products described in this Specification are intended for use in the following electronic and electrical equipment which has normal reliability requirements.
- · Computers · OA equipment · Communications equipment(Terminal devices)
- · Measurement equipment
- · Machine tools
- · AV equipment
- · Electrical home appliances · Personal equipment
- · Industrial robots

- etc.
- The products described in this Specification are not designed or manufactured tobe used in equipment or systems used under life-threatening situations. If you are considering using these products in the equipment listed below, first check the system construction and required reliability.
- ·Transportation equipment(automobiles,trains,ships,etc.)
- ·Backbone network equipment

- ·Traffic-signal control equipment
- · Gas alarms, leakage gas auto breakers
- · Submarine repeater equipment
- ·Burglar alarms, fire alarms, emergency equipment
- · Medical equipment

·Nuclear control equipment etc.

Do not use the products in this Specification for equipment requiring strict reliability such as(but not limited to):

· Aerospace equipment · Aeronautical equipment

7.Warnings

- ·The Diodes should be used in products within their absolute maximaum rating(vltage, current, temperature,etc.). The Diodes may be destroyed if used beyond the rating.
- The equipment containing Diodes should have adequate fuses or protection to prevent the equipment from causing secondary destruction.
- ·Use the Diodes within their reliability and lifetime under certain environments or conditions. The Diodes may fail before the target lifetime of your products if used under certain reliability conditions.
- You must design the Diodes to be operated within the specified maximum ratings(voltage, current,temperature,etc.)toprevent possible failure or destruction of devices.
- · Consider the possible temperature rise not only for the junction and case, but also for the leads.
- · Do not directly touch the leads or package of the Diodes while power is supplied or during operation, to avoid electric shock and burns.

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- •The Diodes are made of incombustible material.However,if a Diode fails,it may emit smoke of flame.Also,operating the Diodes near any flammable place or material may cause the Diodes to emit smoke or flame in case the Diodes become even hotter during operation. Design the arrangement to prevent the spread of fire.
- The Diodes should not used in an environment in the presence of acid,organic matter,or corrosive gas(hydrogen sulfide,sulfurous acid gas.)
- The Diodes should not used in an irradiated field since they are not radiation-proof.

Insatallation

- · Soldering involves temperatures which exceed the device storage temperature rating. To avoid device damage and to ensure reliability, observe the following guidelines from the quality assurance standard.
- ·Solder temperature and duration(through-hole package)

Solder	Duration
temperature	
260 ± 5	10 ± 1second
350 ± 10	3.0 ± 0.5 second

- •The immersion depth of the lead should basically be up to the lead stopper and the distance should be a maximum of 1.5mm from the device.
- ·When flow-soldering, take care to avoid immersing the package in the solder bath.
- •Refer to the following torque reference When mounting the device on a heat sink. Excess torque applied to the mounting screw causes damage to the device and weak torque will increase the thermal resistance, both of which conditions may destory the device.

Table 1:Recommended tightening torque

Table 1.Neconfinenced tightening torque						
Package style	Screw	Recommended tightening				
		torque				
TO-220	M3	30-50Ncm				
TO-220F						
TO-3P	M3	40-60Ncm				
TO-3PF						
TO-247						
TO-3PL	M3	60-80Ncm				

- ·The heat sink should have a flatness within \pm 50 μ m and roughness within 10 μ m. Also,keep the tightening torque within the limits of this specification.
- Improper handling may cause isolation breakdown leading to a critical accident.
- ·We recommend the use of thermal compound to optimize the efficiency of heat radiation.It is important to evenly apply the compound and to eliminate any air viods.

Storage

- •The Diodes must be stored at a standard temperature of 5 to 35 and relative humidity of 45 to 75%. If the storage area is very dry, a humidifier may be required. In such a case, use only deionized water or boiled water, since the chlorine in tap water may corrode the leads.
- •The Diodes should not be subjected to rapid changes in temperature to avoid condensation on the suface of the Diodes. Therfore, store the Diodes in a place Where the temperature is steady.
- •The Diodes should not be stored on top of each other, since this may cause excessive external force on the case.
- •The Diodes should not be stored with the lead terminals remaining unprocessed.Rust may cause presoldered connections to go fail during later processing.
- The Diodes should be stored in antistatic containers or shipping bags.

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8.Appendix

- ·These products do not contain PBDOs or PBBs.
- ·These products, assemblies, or components do not contain any of the above-mentioned substances.

Prohibited substances:

CFCs,halon,carbon tetrachloride,1,1,1-trichloroethane(metyl chloroform)

These products, assemblies, or components are not manufactured using any of the above-mentioned substances.

Prohibited substances:

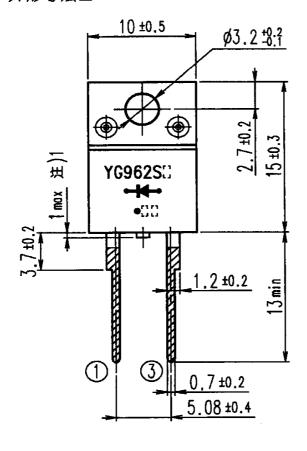
CFCs,halon,carbon tetrachloride,1,1,1-trichloroethane(methyl chloroform)

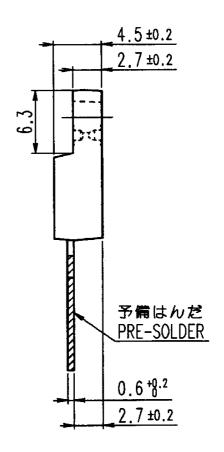
- ·If you have any questions about any part of this Specification, please contact Fuji Electric or its sales agentbefore using the product
- Neither Fuji nor its agents shall be held liable for any injury caused by using the products not in accordance with the instructions.
- The application examples described in this specification are merely typical uses of Fuji Electric products.

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FUJI SILICON DIODE

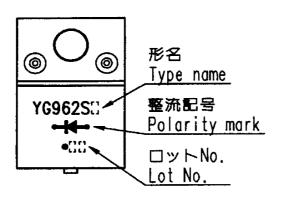
OUT VIEW 外形寸法図 TYPE: YG962SUR





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CONNECTION 結線図

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注)1.端子間 (3端子品におけるセンター 端子部 = 破線部) の樹脂残りは、 1.0mm 以下とする。

> UNIT:mm 寸法単位:mm

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Reverse Characteristic (typ.) Forward Characteristic (typ.) 10¹ Tj=125°C 10 10° Tj=100°C Reverse Current (µA) Tj=150°C 10⁻¹ Forward Current (A) Tj=125°C Tj=100°C Tj=25°C <u>≃</u> 10⁻² Tj=25°C Щ 0.1 10⁻³ 10-4 100 200 300 400 500 600 700 0.01 0.5 4.0 0.0 1.0 1.5 2.0 2.5 3.0 3.5 4.5 VR Reverse Voltage (V) VF Forward Voltage (V) **Reverse Power Dissipation** Forward Power Dissipation 0.024 17 16 0.022 15 350 DC 0.020 14 13 $\widehat{\leq}$ 0.018 12 . 350 € 0.016 Forward Power Dissipation • a • 11 Dissipation Square wave λ=60° 10 0.014 Square wave λ=120° 9 0.012 Reverse Power Sine wave λ=180° 8 α=180° Square wave λ=180°-0.010 6 0.008 ٨k PR 5 0.006 3 0.004 2 0.002 0.000 0 0 100 200 300 400 500 600 700 VR Reverse Voltage (V) lo Average Forward Current (A)

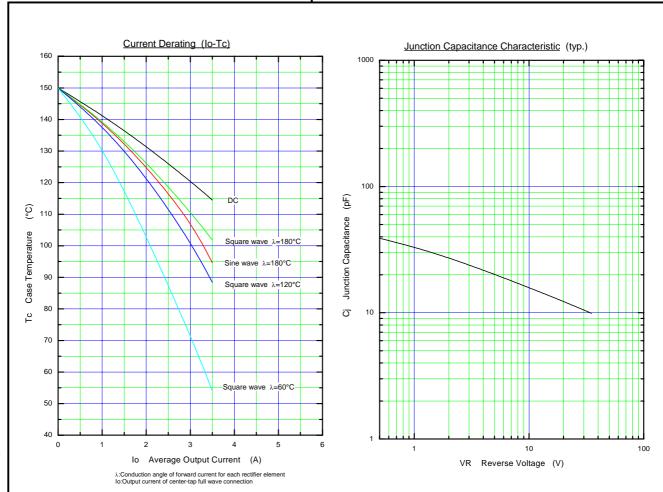
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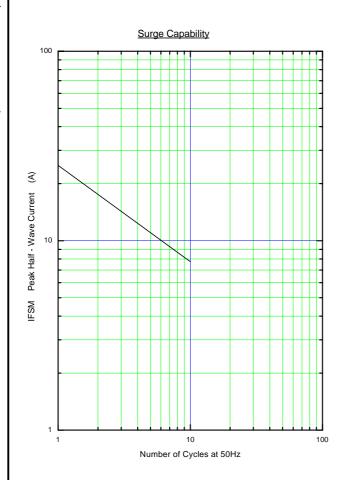
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